

Application Codes in ELV Annex 2	Currently in IMDS	In IMDS after June 17th 2020
<b>Lead and its compounds used as/in</b>		
8(g)(i). Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	8(g) - Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	8(g)(i). Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
8(g)(ii). Lead in solders to complete a viable electrical connection between the semiconductor die and the carrier within integrated circuit flip chip packages where that electrical connection consists of any of the following:  (i) a semiconductor technology node of 90 nm or larger; (ii) a single die of 300 mm <sup>2</sup> or larger in any semiconductor technology node; (iii) stacked die packages with dies of 300 mm <sup>2</sup> or larger, or silicon interposers of 300 mm <sup>2</sup> or larger.		8(g)(ii-i) - Lead in solders to complete a viable electrical connection between the semiconductor die and the carrier within integrated circuit flip chip packages where that electrical connection consists of a semiconductor technology node of 90 nm or larger
		8(g)(ii-ii) - Lead in solders to complete a viable electrical connection between the semiconductor die and the carrier within integrated circuit flip chip packages where that electrical connection consists of a single die of 300 mm <sup>2</sup> or larger in any semiconductor technology node
		8(g)(ii-iii) - Lead in solders to complete a viable electrical connection between the semiconductor die and the carrier within integrated circuit flip chip packages where that electrical connection consists of stacked die packages with dies of 300 mm <sup>2</sup> or larger, or silicon interposers of 300 mm <sup>2</sup> or larger
<b>Lead and its compounds used as/in</b>		
8(k). Soldering of heating applications with 0,5A or more of heat current per related solder joint to single panes of laminated glazings not exceeding wall thickness of 2,1 mm. This exemption does not cover soldering to contacts embedded in the intermediate polymer		8(k) - Soldering of heating applications with 0,5A or more of heat current per related solder joint to single panes of laminated glazings not exceeding wall thickness of 2,1 mm. This exemption does not cover soldering to contacts embedded in the intermediate polymer
<b>Hexavalent chromium and its compounds used as/in</b>		

<p>14. Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0,75 % by weight in the cooling solution:</p> <p>(i) designed to operate fully or partly with electrical heater, having an average utilised electrical power input &lt;75W at constant running conditions;</p> <p>(ii) designed to operate fully or partly with electrical heater, having an average utilised electrical power input <math>\geq 75W</math> at constant running conditions;</p> <p>(iii) designed to fully operate with nonelectrical heater.</p>	<p>14 - Absorption refrigerators in motorcaravans</p>	<p>14(i) - Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0.75% by weight in the cooling solution designed to operate fully or partly with electrical heater, having an average utilised electrical power input &lt;75W at constant running conditions</p> <p>14(ii) - Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0.75% by weight in the cooling solution designed to operate fully or partly with electrical heater, having an average utilised electrical power input <math>\geq 75W</math> at constant running conditions</p> <p>14(iii) - Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0.75% by weight in the cooling solution designed to fully operate with nonelectrical heater</p>
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